

Report NO.: MG00001000113

**1. Product information**

Supplier : JIANGSU CHANGJING ELECTRONICS TECHNOLOGY CO.,LTD.

Part Number :	CJAB14P04
Package Type :	PDFNWB3.3x3.3-8L

**2. MATERIAL ANALYSIS DATA SHEET**

Material	Composition	CAS No.	% of weight	% of weight total
Wafer	Silicon	7440-21-3	100.00%	6.5136%
Lead Frame	Copper	7440-50-8	92.46%	35.5503%
	Iron	7439-89-6	2.50%	
	Lead	7439-92-1	0.01%	
	Phosphorus	7723-14-0	0.02%	
	Zinc	7440-66-6	0.02%	
	Silver	7440-22-4	5.00%	
	Silver Powder	7440-22-4	78.997%	
Die Attach	Epoxy resin	9003-36-5	5.993%	15.1479%
	Diluent A	3101-60-8	3.989%	
	Diluent B	Trade Secret	4.265%	
	Diluent C	Trade Secret	2.10%	
	Hardener A	Trade Secret	1.692%	
	Hardener B	Trade Secret	2.887%	
	Solvent	Trade Secret	0.021%	
	Organic Peroxide	Trade Secret	0.056%	
Wire	Cu	7440-50-8	100.00%	9.084%
Mold Compound	Epoxy Resin 1	Trade Secret	3.50%	28.497%
	Epoxy Resin 2	Trade Secret	2.00%	
	Phenolic Resin	Trade Secret	3.30%	
	Metal Hydroxide	Trade Secret	3.60%	
	Carbon black	1333-86-4	0.20%	
	Amorphous silica1	60676-86-0	81.00%	
	Amorphous silica2	7631-86-9	6.40%	
Plating	Tin	7440-31-5	100.00%	5.2071%

Materials Disclosure Disclaimer: Even though all possible efforts have been made to provide you with the information, It is for guidance only and we cannot guarantee to its accuracy or completeness.